

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Amended) A CVD apparatus comprising:
a vacuum vessel separated into two chambers;
the first one of the two chambers containing a radio-frequency electrode;
the second one of the two chamber containing a substrate support
mechanism for mounting a substrate;
wherein said vacuum vessel is separated by an electrically conductive
partitioning section, said partitioning section comprising:
a plurality of through-holes to allow communication between the first chamber
and the second chamber;
an interior space for receiving a reactive gas, the interior space separated
from the first chamber and communicating with the second chamber through a
plurality of diffusion holes; and
a heater for heating the electrically conductive ~~partition~~ partitioning section.
2. (Original) The apparatus of claim 1, further comprising:
an electrically conductive spiral shield; and
wherein the partitioning section is mounted to the vacuum vessel by means of
a mounting screw such that electrical contact between the partitioning section and
the vacuum vessel is achieved through said spiral shield.

3. (Original) A CVD apparatus comprising:
 - a vacuum vessel separated into two chambers;
 - at least one radio-frequency electrode contained in a first one of said two chambers;
 - a substrate support mechanism contained in the second one of said two chambers;
 - an electrically conductive partition section;
 - an electrically conductive spiral shield; and
 - wherein said vacuum vessel is separated into two chambers by said electrically conductive partition section which is mounted to said vacuum vessel by means of a mounting screw such that electrical contact between the partitioning section and the vacuum vessel is achieved through said spiral shield.
4. (New) The apparatus of claim 1, wherein the heater is adapted to heat the partitioning section to at least 100°C.
5. (New) The apparatus of claim 1, wherein the heater is adapted to heat the partitioning section to at least 200°C.
6. (New) The apparatus of claim 1, wherein the heater is adapted to heat the partitioning section to a temperature at which the adsorption of fluorine onto an inner circumferential face of the through-holes and a surface of the partitioning section is suppressed.